



# IRF624B/IRFS624B

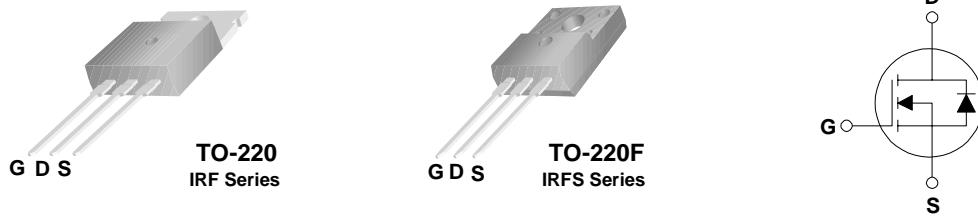
## 250V N-Channel MOSFET

### General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters and switch mode power supplies.

### Features

- 4.1A, 250V,  $R_{DS(on)} = 1.1\Omega$  @  $V_{GS} = 10$  V
- Low gate charge ( typical 13.5 nC)
- Low  $C_{rss}$  ( typical 9.5 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



### Absolute Maximum Ratings

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	IRF624B	IRFS624B	Units	
$V_{DSS}$	Drain-Source Voltage	250		V	
$I_D$	Drain Current - Continuous ( $T_C = 25^\circ\text{C}$ )	4.1	4.1 *	A	
	- Continuous ( $T_C = 100^\circ\text{C}$ )	2.6	2.6 *	A	
$I_{DM}$	Drain Current - Pulsed	(Note 1)	16.4	16.4 *	A
$V_{GSS}$	Gate-Source Voltage		$\pm 30$	V	
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)	75	mJ	
$I_{AR}$	Avalanche Current	(Note 1)	4.1	A	
$E_{AR}$	Repetitive Avalanche Energy	(Note 1)	4.9	mJ	
$dv/dt$	Peak Diode Recovery $dv/dt$	(Note 3)	5.5	V/ns	
$P_D$	Power Dissipation ( $T_C = 25^\circ\text{C}$ )	49	34	W	
	- Derate above $25^\circ\text{C}$	0.39	0.27	W/ $^\circ\text{C}$	
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$	
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	$^\circ\text{C}$	

\* Drain current limited by maximum junction temperature.

### Thermal Characteristics

Symbol	Parameter	IRF624B	IRFS624B	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case Max.	2.54	3.7	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	--	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient Max.	62.5	62.5	$^\circ\text{C}/\text{W}$

## Electrical Characteristics

$T_C = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$	250	--	--	V
$\Delta \text{BV}_{\text{DSS}} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to $25^\circ\text{C}$	--	0.26	--	$\text{V}/^\circ\text{C}$
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 250 \text{ V}$ , $V_{\text{GS}} = 0 \text{ V}$	--	--	10	$\mu\text{A}$
		$V_{\text{DS}} = 200 \text{ V}$ , $T_C = 125^\circ\text{C}$	--	--	100	$\mu\text{A}$
$I_{\text{GSSF}}$	Gate-Body Leakage Current, Forward	$V_{\text{GS}} = 30 \text{ V}$ , $V_{\text{DS}} = 0 \text{ V}$	--	--	100	nA
$I_{\text{GSSR}}$	Gate-Body Leakage Current, Reverse	$V_{\text{GS}} = -30 \text{ V}$ , $V_{\text{DS}} = 0 \text{ V}$	--	--	-100	nA

## On Characteristics

$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}} = V_{\text{GS}}$ , $I_D = 250 \mu\text{A}$	2.0	--	4.0	V
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}} = 10 \text{ V}$ , $I_D = 2.05 \text{ A}$	--	0.84	1.1	$\Omega$
$g_{\text{FS}}$	Forward Transconductance	$V_{\text{DS}} = 40 \text{ V}$ , $I_D = 2.05 \text{ A}$ (Note 4)	--	4.0	--	S

## Dynamic Characteristics

$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}} = 25 \text{ V}$ , $V_{\text{GS}} = 0 \text{ V}$ , $f = 1.0 \text{ MHz}$	--	350	450	pF
$C_{\text{oss}}$	Output Capacitance		--	45	59	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	9.5	13	pF

## Switching Characteristics

$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}} = 125 \text{ V}$ , $I_D = 4.1 \text{ A}$ , $R_G = 25 \Omega$	--	6.5	25	ns
$t_r$	Turn-On Rise Time		--	35	80	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	40	90	ns
$t_f$	Turn-Off Fall Time		--	35	80	ns
$Q_g$	Total Gate Charge	$V_{\text{DS}} = 200 \text{ V}$ , $I_D = 4.1 \text{ A}$ , $V_{\text{GS}} = 10 \text{ V}$	--	13.5	18	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	2.0	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	6.5	--	nC

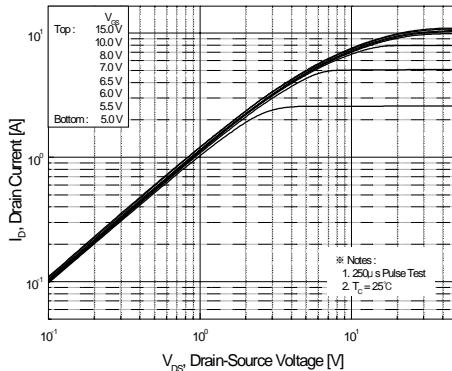
## Drain-Source Diode Characteristics and Maximum Ratings

$I_S$	Maximum Continuous Drain-Source Diode Forward Current	--	--	4.1	A	
$I_{\text{SM}}$	Maximum Pulsed Drain-Source Diode Forward Current	--	--	16.4	A	
$V_{\text{SD}}$	Drain-Source Diode Forward Voltage	$V_{\text{GS}} = 0 \text{ V}$ , $I_S = 4.1 \text{ A}$	--	--	1.5	V
$t_{\text{rr}}$	Reverse Recovery Time	$V_{\text{GS}} = 0 \text{ V}$ , $I_S = 4.1 \text{ A}$ , $dI_F / dt = 100 \text{ A}/\mu\text{s}$	--	145	--	ns
$Q_{\text{rr}}$	Reverse Recovery Charge		--	0.7	--	$\mu\text{C}$

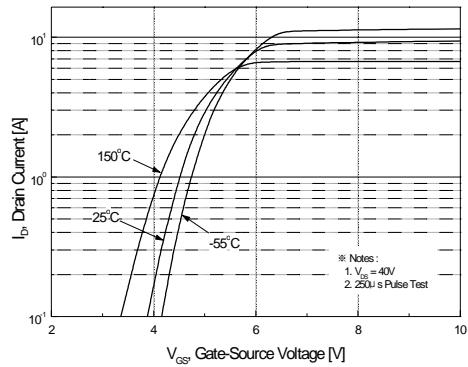
### Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2.  $L = 7.1\text{mH}$ ,  $I_{AS} = 4.1\text{A}$ ,  $V_{DD} = 50\text{V}$ ,  $R_G = 25 \Omega$ , Starting  $T_J = 25^\circ\text{C}$
3.  $I_{SD} \leq 4.1\text{A}$ ,  $dI/dt \leq 300\text{A}/\mu\text{s}$ ,  $V_{DD} \leq \text{BV}_{\text{DSS}}$ , Starting  $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width  $\leq 300\mu\text{s}$ , Duty cycle  $\leq 2\%$
5. Essentially independent of operating temperature

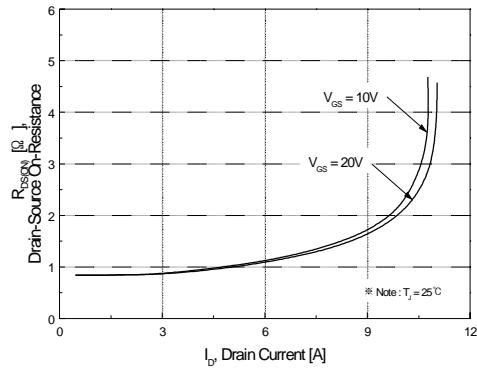
## Typical Characteristics



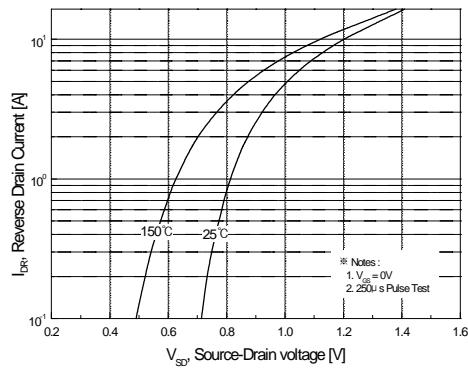
**Figure 1. On-Region Characteristics**



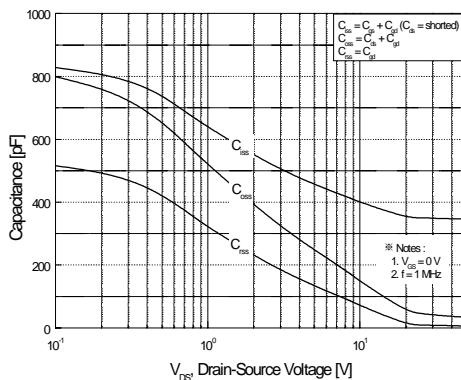
**Figure 2. Transfer Characteristics**



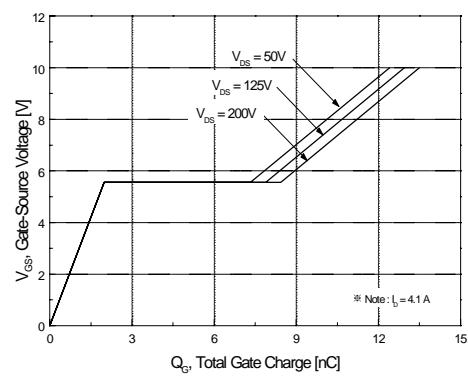
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**



**Figure 5. Capacitance Characteristics**



**Figure 6. Gate Charge Characteristics**